

Electronic Patent Application Fee Transmittal				
Application Number:		10552540		
Filing Date:		11-Oct-2005		
Title of Invention:		THERMOSETTING RESIN COMPOSITION, MULTILAYER BODY USING SAME, AND CIRCUIT BOARD		
First Named Inventor/Applicant Name:		Shigeru Tanaka		
Filer:		Dariush G. Adli/Reynaldo Gallardo		
Attorney Docket Number:		81844.0044		
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
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Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

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Printed copy of patent - no color	8001	4	3	12
Total in USD (\$)				1822